

This listing of claims will replace all prior versions, and the listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A method, comprising:

spinning a substrate having a film;

scanning an optical sensor directly over and along across a path over along a surface of the substrate, the path establishing a spiral having greater than one full rotation over the surface of the substrate;

sensing properties of the film with the optical sensor at a plurality of points along the path; and

generating a map of the film using information from the plurality of points along the path covering ~~substantially an entire~~ the surface of the substrate at each of the plurality of points along the spiral established by the path;

wherein the generating of the map includes performing analysis of light reflected off the surface of the substrate and applying the results in one of a graphical representation or a text format representation.

2. (Currently amended) The method of claim 1, wherein the path of the scanning is from the edge of the substrate to the center of the substrate affecting ~~[[a]]~~ the path over the surface of the substrate.

3. (Original) The method of claim 1, wherein the path of the scanning is from the center of the substrate to the edge of the substrate affecting a reverse path over the surface of the substrate.

4. (Original) The method of claim 1, wherein the sensing properties of the film with the optical sensor includes the gathering of light reflected off the surface of the substrate.

5. (Cancelled)

6. (Currently amended) The method of claim 1, further comprising;

scanning an inductive sensor across the ~~the~~ path along the surface of the substrate.

7. (Original)The method of claim 6, wherein the path of the scanning is from the edge of the substrate to the center of the substrate affecting a path over the surface of the substrate.

8. (Original) The method of claim 6, wherein the path of the scanning is from the center of the substrate to the edge of the substrate affecting a reverse path over the surface of the substrate.

9. (Original) The method of claim 6, wherein the inductive sensor is capable of providing material properties of conductive materials on the surface of the substrate.

10. (Original) The method of claim 6, wherein the generating a map includes information obtained from the optical sensor and the inductive sensor provided in one of a graphical representation and a text format representation.

11. (Currently Amended) A method, comprising:

scanning an inductive sensor directly over and along ~~a~~ across a path defined over ~~along~~ a surface of a substrate having a film when the substrate is spinning, the path establishing a spiral having greater than one full rotation over the surface of the substrate;

sensing properties of the film with the inductive sensor at a plurality of points along the path covering ~~substantially an entire~~ the surface of the substrate at each of the plurality of points along the spiral established by the path;

averaging two or more of the sensed properties from two or more of the plurality of points along the path; and

generating a map of the film using information from the plurality of points along the path, wherein some data in the generated map includes data resulting from the averaging of two or more sensed properties.

12. (Currently amended) The method of claim 11, wherein the path of the scanning is from the edge of the substrate to the center of the substrate affecting the ~~the~~ path over the surface of the substrate.

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13. (Original) The method of claim 11, wherein the path of the scanning is from the center of the substrate to the edge of the substrate affecting a reverse path over the surface of the substrate.

14.-18. (Cancelled)

19. (Previously presented) The method of claim 11, wherein the inductive sensor is capable of providing material properties of conductive materials on the surface of the substrate.

20. (Previously presented) The method of claim 11, wherein the generating a map includes information obtained from the optical sensor and the inductive sensor provided in one of a graphical representation and a text format representation.

21. (Currently Amended) A method for inspecting surface properties of materials of a semiconductor wafer, comprising:

scanning a combined an optical sensor and an inductive sensor directly over and along a path defined over a region that is to define a surface of a substrate that can have a film of the semiconductor wafer, the ~~substrate~~ semiconductor wafer being configured to spin when present, and the path establishing a spiral over the surface of the semiconductor wafer; and

sensing properties of the film at a plurality of points along the path covering ~~substantially an entire~~ the surface of the ~~substrate~~ semiconductor wafer; and

generating a map of the film using information from the plurality of points along the path.

22. (Currently amended) The method of claim 21, wherein the path of the scanning is from the edge of the ~~substrate~~ semiconductor wafer to the center of the substrate affecting ~~[[a]]~~ the path over the surface of the ~~substrate~~ semiconductor wafer.

23. (Currently amended) The method of claim 21, wherein the path of the scanning is from the center of the ~~substrate~~ semiconductor wafer to the edge of the ~~substrate~~ semiconductor wafer affecting a reverse path over the surface of the ~~substrate~~ semiconductor wafer.

24. (Currently amended) The method of claim 21, wherein the sensing properties of the film with an ~~the~~ optical sensor part of the combined optical and inductive sensor includes the gathering of light reflected off the surface of the ~~substrate~~ semiconductor wafer.

25. (Currently amended) The method of claim 21, wherein the generating a map is accomplished by performing analysis of light reflected off the surface of the ~~substrate~~ semiconductor wafer and applying the results in one of a graphical representation and a text format representation.

26.-28. (Cancelled)

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29. (Currently Amended) The method of claim 21, wherein ~~the~~ an inductive sensor part of the combined optical and inductive sensor is capable of providing material properties of conductive materials on the surface of the ~~substrate~~ semiconductor wafer.

30. (Currently Amended) The method of claim 21, wherein the generating ~~[[a]]~~ the map includes information obtained from the combined optical and inductive sensor ~~optical sensor and the inductive sensor~~ is provided in one of a graphical representation and a text format representation.

31.-41. (Cancelled)

42. (Currently amended) A method, comprising:

spinning a substrate having a film;

moving an arm having a first end and a second end, the second end having a sensor thereon, the arm being moved directly over a surface of the substrate without having another structure between the sensor and the surface of the wafer;

scanning an arm across a path ~~from~~ between an edge of the substrate ~~to~~ and the center of the substrate along the ~~[[a]]~~ surface of the substrate, the arm having ~~a~~ an optical sensor and an inductive sensor therein and the path establishes a spiral over the surface of the substrate;

sensing properties of the film ~~with the optical sensor and the inductive sensor~~ at a plurality of points along the path covering ~~substantially an entire~~ the surface of the substrate;
and

generating a map of the film using information from the plurality of points along the path.

43. (Currently amended) The method of claim 42, wherein the generating of the map is accomplished by performing an analysis of information obtained from the ~~optical sensor and the inductive sensor~~ and displayed in one or both of a graphical representation and a text format representation.